

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION OF

Inventor(s): Talieh, et al.

Filed: Herewith

Title: Method and Apparatus for Plating and Polishing a Semiconductor Substrate

August 28, 2001

PRELIMINARY AMENDMENTHon. Commissioner of Patents
Washington, D.C. 20231

Sir:

Please amend this application as follows:

IN THE SPECIFICATION:

At the top of the first page, just under the title, insert:

-- This is a Divisional Application of U.S. application No. 09/285,621 filed April 3, 1999. --

Respectfully submitted,

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Date of Deposit: August 28, 2001

I certify that this paper and listed enclosures are being deposited with the U.S. Post Office "Express Mail Post Office to Addressee" under 35 CFR 1.10 on the above date, addressed to the Commissioner for Patents, Box Application, Washington, D.C. 20231
Margaret M. Hasson